

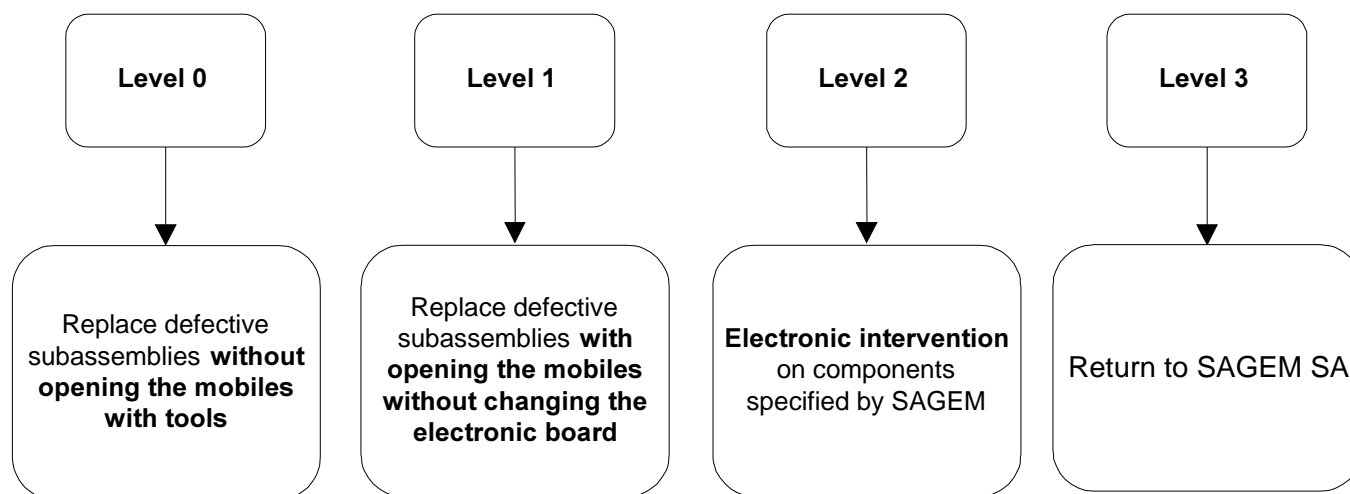
## CHAPTER 5 - MAINTENANCE PROCEDURES

### 5.1 TECHNICAL WORK LEVELS

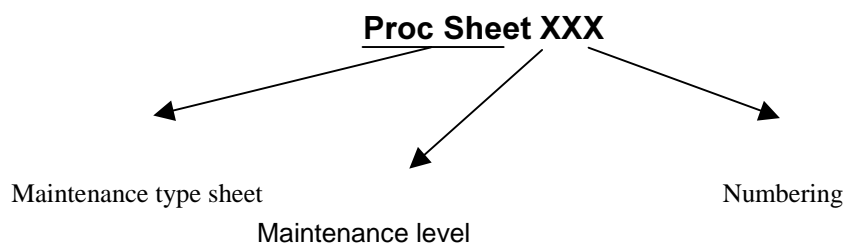
There are four technical work levels:

- Level 0,
- Level 1,
- Level 2,
- Level 3.

Each level represents a maintenance degree that depends on which elements are to be removed.



Maintenance procedure sheets are coded as follows :



## **5.2 SHORT LOOP PROCESS**

### **1. Initialisation**

From the communication by Sagem and the reception of the concerned products by the short loop process, the Repair Centre shall comply with the above procedure. The application of the Short loop process will end when received the authorisation of repairing given by Sagem.

### **2. Administrative checks to be done by the Repair Centre**

- Authorisation from Sagem for treating the reference received (Part number)
- Process to be applied : short loop process or normal process (DTS, Normal, etc...). The Repair Centre shall check if the product received has to be treated according to the short loop process.
- Controls on the warranty conditions and DOA conditions (if the Repair Centre is authorised) communicated by Sagem.

### **3. Tests and controls :**

- Checks if there are no external shocks or oxidation marks ( the covers shall be dismantled in case of exchangeable covers)
- Checks and confirmation of the defect (real call with SIM, functional test keypad , display, vibrating device, etc...)
- Check the concordance between the defect declared by the end-user and the defect observed
- Call back of the end-user or dealer (as far as possible) either in case of misunderstanding of the defect declared by the end-user or in case of the non observation of the defect. (see the appendix "Additional information about the No Fault Found –NFF- " at the end of this document allowing according to the case to understand the return of the product)

If any doubts occurred concerning out of warranty products received, the Repair Centre shall send to Sagem Montauban (with knowledge to the Area Manager and Support Engineer) the photo of the defect.

#### **N.B :**

- The handsets shall not be dismantled (by using screwdrivers) except previous request from Sagem.
- The Repair Centre will not make any Repair (such as spare parts exchange or software upgrade) except previous communication of Sagem. The exchanges of handsets or accessories are the only intervention authorised.

### **4. Exchange by the Repair Centre**

- The Repair Centre will use the products delivered for swap to the Repair Centre for exchanging the products to the end-users (except particular process defined by Sagem).
- The under- warranty handsets and accessories received shall be exchanged to the end-user.
- The under- warranty handsets and accessories declared No Fault Found (NFF) shall be exchanged to the end-users except previous communication of Sagem.
- The Out of warranty handsets and accessories (oxidation, shocks, ...) will be repaired by the Repair Centre after acceptance by the customer of an estimate according to the Sagem out of warranty repair prices communicated.
- **The under- warranty and out of warranty handsets shall be sent to Sagem Montauban.**
- In the frame of the Short loop process, there is no level 1 (L1) intervention

### **5. Reports**

An exchange of an handset and its accessories shall be codified Level 3 (L3)

An accessory exchange shall be codified Level 0 (L0).

The Repair Centre shall capture all the information required for issuing and sending the Repair Reports and Status reports according to the Contractual frequency defined. The Reports shall includes the products treated by the Repair Centre under- warranty or out of warranty.

## 6. Procedure

From the beginning date of the Short loop process application and **minimum each week, the Repair Centre shall ship the products (handsets and accessories) to Sagem Montauban.**

### 61. Handsets :

- MRA Procedure for the after-Sales products ( one MRA number for the products concerned by the short loop).
- MRA Procedure for DOA products ( one MRA DOA number for the products concerned by the short loop) if the Repair Centre is authorised to treat the DOA products.

The MRA request shall be sent to Sagem Montauban (with knowledge to the Area Manager and Support Engineer).

The shipment of products to Sagem Montauban shall comply with the MRA procedure. Furthermore each products shall be sent with the Return Product Sheet filled in indicating the defect declared by the end-user and the defect observed by the Repair Centre (Sagem Defect codes).

The NFF products sent to Sagem Montauban shall be identified by using separate package. Furthermore this products shall be sent with the complete description of the defect declared by the end-user ( not codified).

The accessories received by the Repair Centre shall be sent to Sagem Montauban sent back attached with the handset ( not connected to the handset).

### 62. Accessories :

For the accessories received without the handsets, the procedure is the following:

Accessories return procedure to Sagem Montauban to be used. The Repair Centre shall indicate on the parcel Accessories + model (ex : myX 2-2) for the accessories received in the Repair Centre without the handsets.

## 7. Sagem Montauban

Sagem Montauban will ship back to the Repair Centre the same quantity of handsets and accessories as the quantity received.

## 8 Additional information about the no fault found

In any case: Ask to the end-user the frequency of the defect and the circumstances of its apparition (during an incoming or out-going call, while playing, while downloading, etc.). Try to answer the questions: Where? When? How?

- If the customer complains about a **“Power supply / charging”** failure : (shutting down of the mobile, problem of booting, etc.);
  - During which operation ? In which circumstances ?
  - What is the state of the battery and the charger before shipment to the repair centre ?
  - If the mobile shuts down by itself, must he enter his code pin, adjust the date and the hour when rebooting the phone?
- If the customer complains about a communication problem:
  - What are his residence zone and the reception level of the mobile (Number of receipt bar);
  - What is the state of the battery when the defect appears?
  - In case of loss of communication :
    - With or without total extinction of the mobile?
    - Does the loss of communication occur always in the same place and with the same person?
    - Does the loss of communication occur while browsing in the menus, during the communication, or during playing or downloading?
- If the customer complains about a problem of blockage of key of the keyboard:
  - In which circumstances does the problem occur?
  - Did he activate the keypad locking ?
  - Did he change or remove the upper cover ?
  - Which are the non functioning keys ?

## 5.2 MAINTENANCE TOOLS

The following tools are necessary to carry out maintenance operations :

- Electrical screwdrivers with tightening torque settings **(0.25 NM)** ,equipped with 0,6 mm Torx .
- Metal dome jig.
- Plastic Tweezers.
- Gloves
- ESD protection strap

# LEVEL 0 MAINTENANCE

	<b>REMOVING / REPLACING BACK COVER</b>	Proc Sheet 0 01
myX 2-2		1/1

**Tools :**

Not applicable.

**Preliminary operation**

Turn the handset upside down

**Removal procedure :**

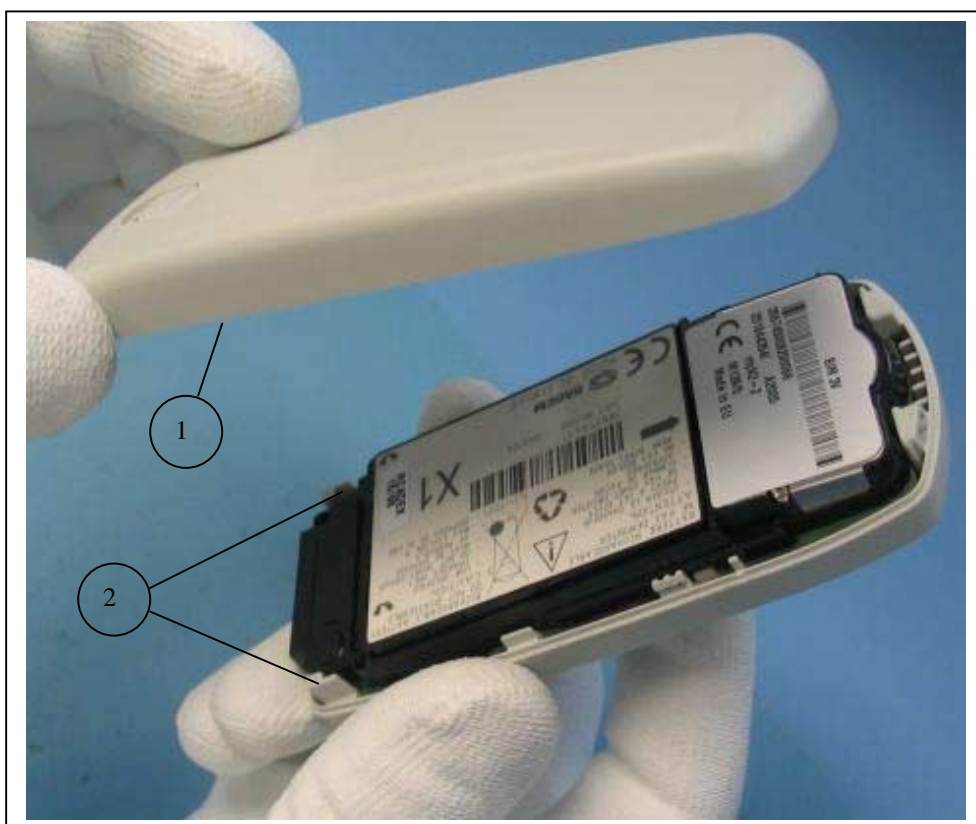
- 1 Unlock the back cover (1) , by pushing the lock buttons (2) upwards.
- 2 Remove rear cover (1) by lifting bottom end first

**Placement procedure :**

1. Replace the cover by engaging top hooks first .
2. Push down back of rear cover and push button back into locked position

**Further operations :**

1. Check the covers are assembled tightly



	<b>REMOVING / REPLACING THE BATTERY</b>	Proc Sheet 0 02
myX 2-2		1/1

**Tools :**

- Not applicable

**Preliminary operation :**

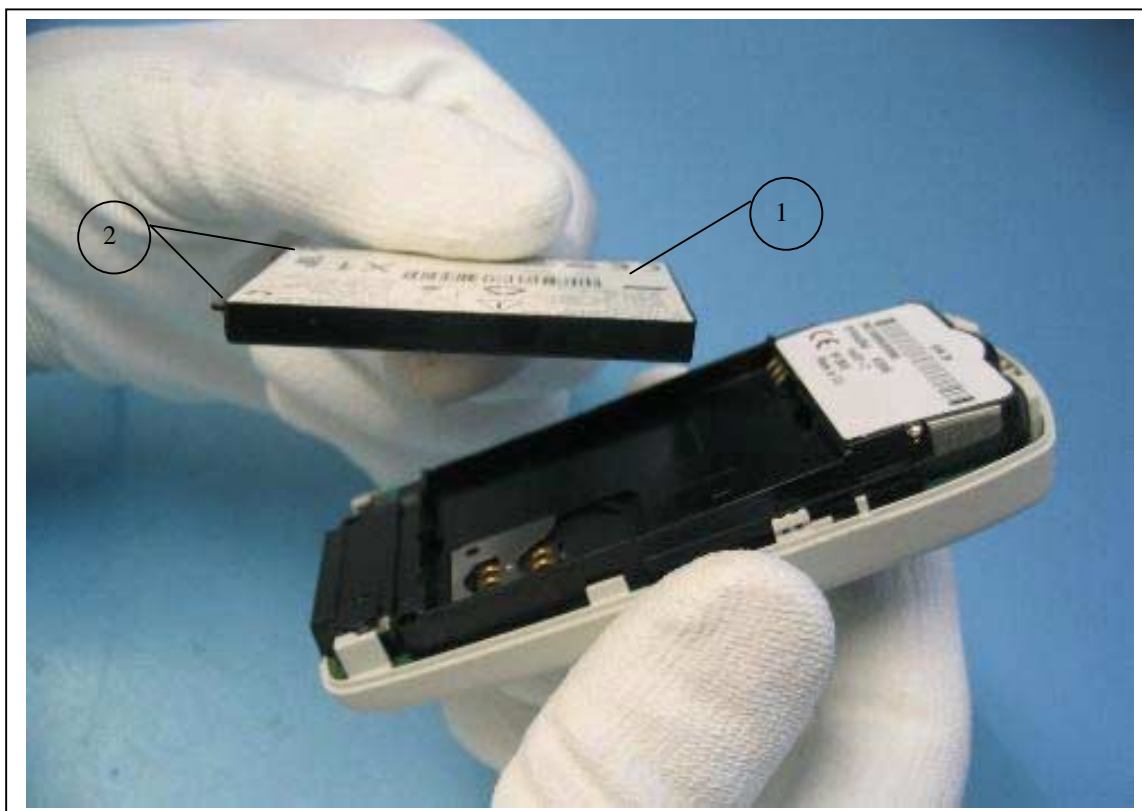
- Switch off the mobile phone

**Removal procedure :**

1. Remove the back cover ( [Proc sheet 0 01](#)).
2. Take out the battery (1) by first extracting the stop pins (2).

**Placement procedure :**

1. Place the battery by first inserting the upper section.
2. Place the back cover ([Proc sheet 0 01](#)).



	<b>REMOVING / REPLACING THE FRONT COVER</b>	Proc Sheet 0 03
myX 2-2		1/1

**Tools :**

- Not applicable

**Preliminary operation :**

1. Remove the back cover ( [Proc sheet 0 01](#)).

**Removal procedure :**

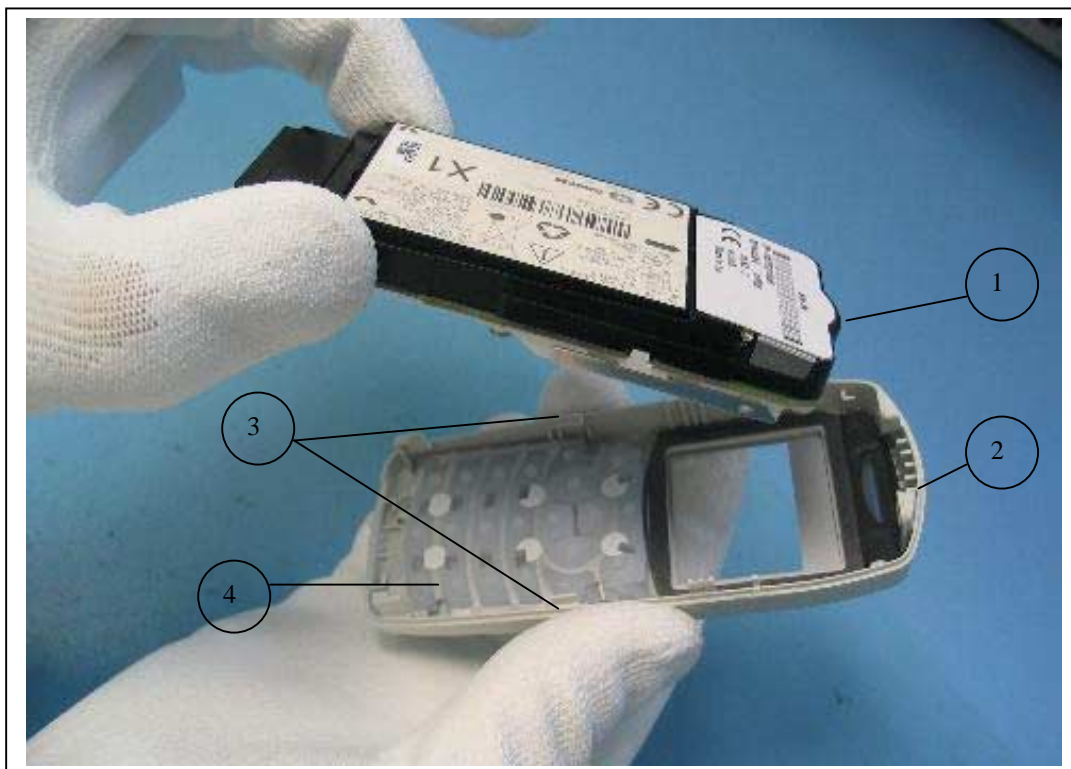
1. Separate the two front cover (2) fixing stop pins (3) to release the electronic module (1).
2. Remove the equipped front cover (2).
3. Remove the elastomer keypad (4).

**Placement procedure :**


1. On the new front cover (2), position the elastomer keypad (4) in position, ensuring it is free of dust.
2. Place the module (1) onto front cover (2) ,engaging firstly the module top, then press on the module top (1)

**Further operations**

1. Place the back cover ([Proc sheet 0 01](#)).





	<b>REMOVING / REPLACING THE ELASTOMER KEYPAD</b>	Proc Sheet 0 04
myX 2-2		1/1

**Tools :**

- Not applicable

**Preliminary operation**

1. Remove the back cover ( [Proc sheet 0 01](#)).
2. Remove the front cover ( [Proc sheet 0 03](#)).

**Removal procedure :**

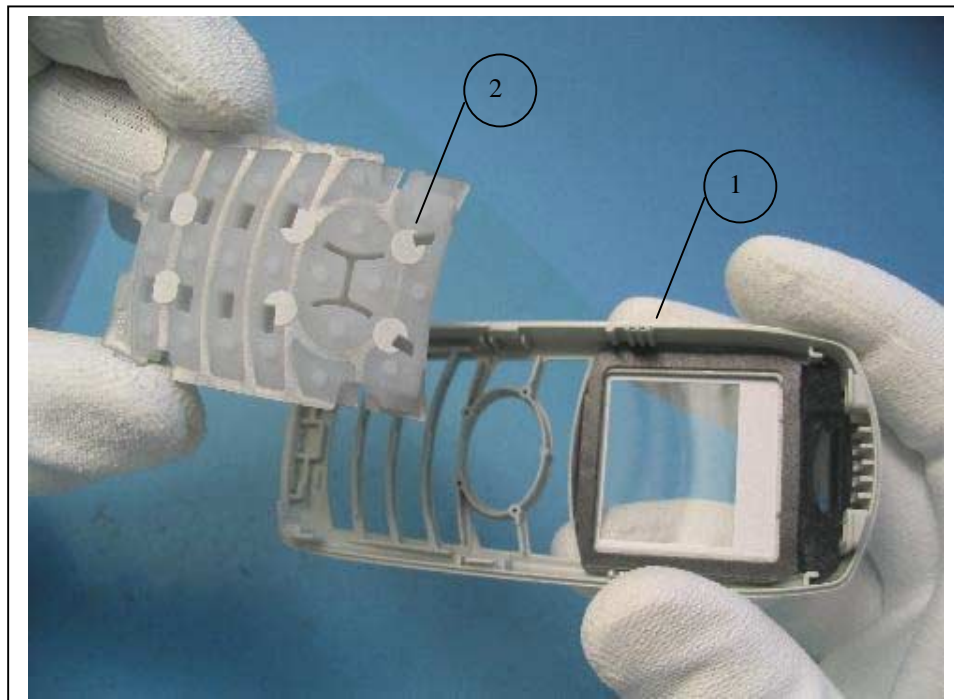
1. Remove the elastomer keypad (2) from the front cover (1).

**Placement procedure :**

1. Clean the elastomer keypad (2) with compressed air.
2. Place the elastomer keypad (2) in position in its housing

**Further operations :**

1. Replace the front cover ( [Proc sheet 0 03](#)).
2. Replace the back cover ( [Proc sheet 0 01](#)).



# **LEVEL 1 MAINTENANCE**

	REMOVING / REPLACING THE DISPLAY	Proc Sheet 1 02
myX 2-2		1/2

#### **Tools :**

- A 0.6mm torx screwdriver
- gloves

- **This procedure must be performed by a technician provided with gloves , to avoid any risk of pollution.**
- **Contacts of display must be never touched.**

#### **Preliminary operation**

1. Remove the back cover ( [Proc sheet 0 01](#)).
2. Remove the battery ( [Proc sheet 0 02](#)).
3. Remove the front cover ( [Proc sheet 0 03](#)).

#### **Removal procedure :**

1. On the electronic equipped module , unscrew the four attachment screws (4) .
2. Remove the assembly display (2) (3).
3. Turn the display round (3) to the top of the electronic board (1).
4. Push on the flex PCB (5) to liberate the display board to board connector.
5. Remove the display (3).

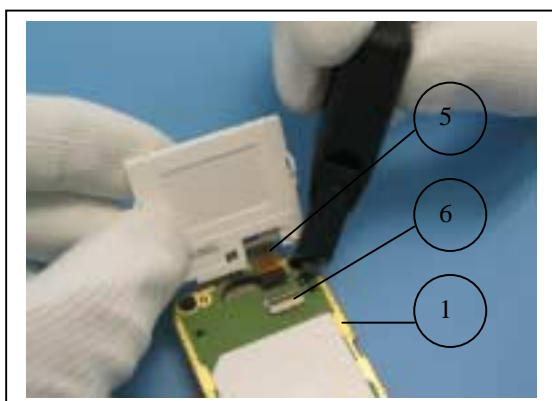
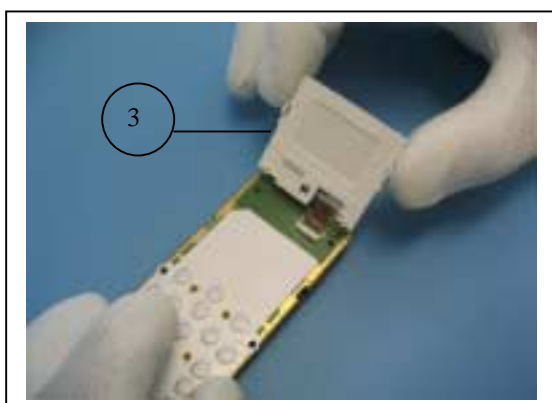
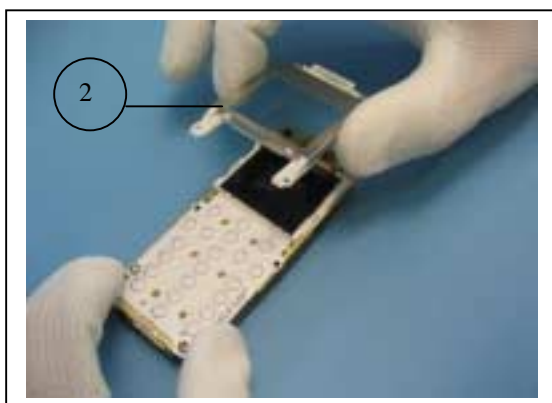
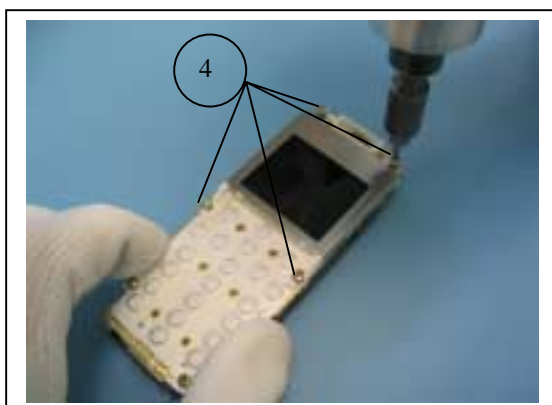
#### **Placement procedure :**


1. Position the display (3) in its housing first.
2. Position the display board to board connector on the electronic board connector (6) and press into locked position.
3. Replace the display (3) of the support (2),beginning with the bottom.
4. Replace the assembly display (2) (3) on the electronic equipped module (1).
5. Position and tighten the four attachments screws with **0,25 N.m** torque.
6. Verify that there are no impurities on the display.

#### **Further operations :**

1. Replace the front cover ([Proc sheet 0 03](#)).
2. Replace the battery ([Proc sheet 0 02](#)).
3. Replace the back cover ([Proc sheet 0 01](#)).
4. Carry out the radio test ([Test Sheet 06](#)).

	<b>REMOVING / REPLACING THE DISPLAY</b>	Proc Sheet 1 02
myX 2-2		2/2



	<b>REMOVING / REPLACING THE LIGHT GUIDE KEYPAD</b>	Proc Sheet 1 03
myX 2-2		1/1

**Tools :**

- A 0.6mm torx screwdriver

**Preliminary operation**

1. Remove the back cover ( [Proc sheet 0 01](#)).
2. Remove the battery ( [Proc sheet 0 02](#)).
3. Remove the front cover ( [Proc sheet 0 03](#)).

**Removal procedure :**

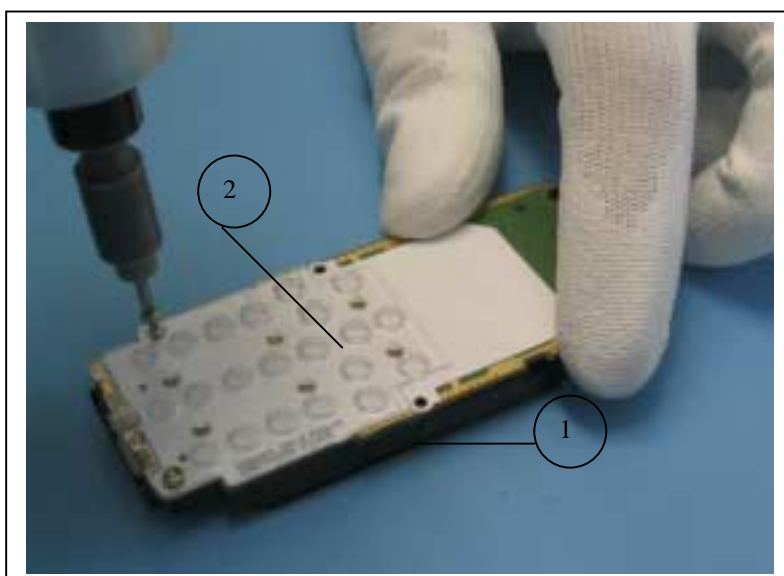
1. Unscrew the six attachment screws on the assembly plate (1)
2. Remove the assembly display ([Proc sheet 1.02](#))
3. Remove the light guide keypad (2).

**Placement procedure :**

1. Replace the new light guide keypad on its housing.
2. Replace the assembly display ([Proc sheet 1.02](#))
3. Position and tighten the six attachments screws with **0,25 N.m** torque.

**Further operations :**

1. Replace the front cover ([Proc sheet 0 03](#)).
2. Replace the battery ([Proc sheet 0 02](#)).
3. Replace the back cover ([Proc sheet 0 01](#)).
4. Carry out radio test ([Test Sheet 06](#)).



	<b>REMOVING / REPLACING THE ELECTRONIC BOARD</b>	Proc Sheet 1 04
myX 2-2		1/1

**Tools :**

- A 0.6mm torx screwdriver

**Preliminary operation**

1. Remove the back cover ( [Proc sheet 0 01](#)).
2. Remove the battery ( [Proc sheet 0 02](#)).
3. Remove the front cover ( [Proc sheet 0 03](#)).

**Removal procedure :**

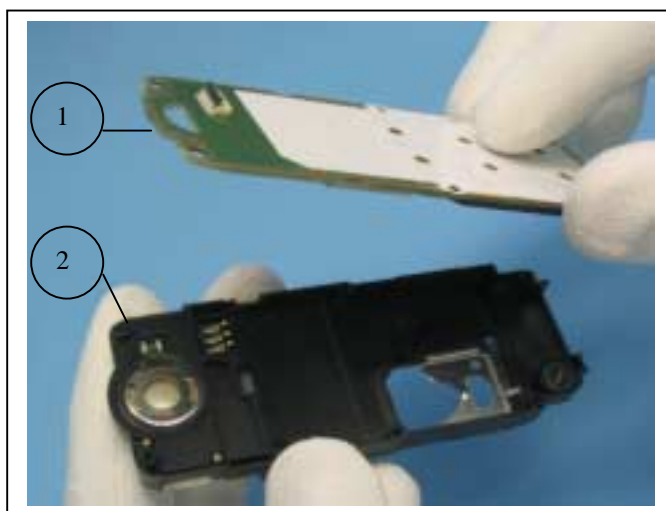
1. Unscrew the six attachment screws on the assembly plate (2)
2. Remove the assembly display ([Proc sheet 1 02](#))
3. Remove the light guide keypad ([Proc sheet 1 03](#))
4. Remove the electronic board (1) on the assembly plate (2).([Proc sheet 1 10](#))

**Placement procedure :**

1. Replace the new electronic board on the assembly plate (2).([Proc sheet 1 10](#))
2. Replace the light guide keypad on its housing.
3. Replace the assembly display ([Proc sheet 1.02](#))
4. Position and tighten the six attachments screws with **0,25 N.m** torque.

**Further operations :**

1. Replace the front cover ([Proc sheet 0 03](#)).
2. Replace the battery ([Proc sheet 0 02](#)).
3. Replace the back cover ([Proc sheet 0 01](#)).
4. Carry out the radio test ([Test Sheet 06](#)).



	REMOVING / REPLACING THE METAL DOME	Proc Sheet 1 05
myX 2-2		1/1

#### **Tools :**

- A 0.6mm torx screwdriver
- Gloves
- Metal dome Jig
- Tweezers

#### **Preliminary operation**

**This procedure must be performed by a technician with gloves.**

1. Remove the back cover ( [Proc sheet 0 01](#)).
2. Remove the battery ( [Proc sheet 0 02](#)).
3. Remove the front cover ( [Proc sheet 0 03](#)).
4. Unscrew the six attachment screws on the electronic board (1)
5. Remove the assembly display ([Proc sheet 1 02](#)), then the light guide keypad ([Proc sheet 1 03](#))

#### **Removal procedure :**

1. Lift up the metal dome (2) on the electronic card (1) with tweezers.

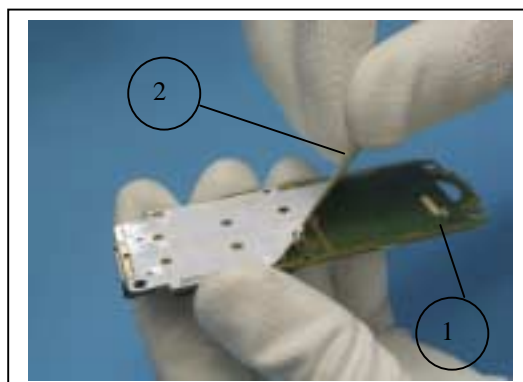
#### **Placement procedure :**

**Warning : The metal dome is not reusable, it must be necessarily replaced by a new metal dome, unless the board is swapped and sent as level 3**

1. Replace the metal dome on the electronic card, using the metal dome jig.

#### **Further operations :**

1. Replace the new electronic board on the assembly plate (2).([Proc sheet 1.04](#))
2. Replace the light guide keypad ([Proc sheet 1.03](#))
3. Replace the assembly display ([Proc sheet 1.02](#))
4. Position and tighten the six attachments screws with torque settings of **0,25 N.m.**
5. Replace the front cover ([Proc sheet 0 03](#)).
6. Replace the battery ([Proc sheet 0 02](#)).
7. Replace the back cover ([Proc sheet 0 01](#)).
8. Carry out the radio test ([Test Sheet 06](#)).



	<b>REMOVING / REPLACING THE SIM LOCKER</b>	Proc Sheet 1 06
myX 2-2		1/1

**Tools :**

- A 0.6mm torx screwdriver

**Preliminary operation :**

1. Remove the back cover ( [Proc sheet 0 01](#)).
2. Remove the battery ( [Proc sheet 0 02](#)).
3. Remove the SIM card .
4. Remove the front cover ( [Proc sheet 0 03](#)).
5. Unscrew the six attachment screws on the electronic board .
6. Remove the assembly display ([Proc sheet 1 02](#))
7. Remove the light guide keypad ([Proc sheet 1 03](#))
8. Remove the electronic board.([Proc sheet 1 04](#))

**Removal procedure :**

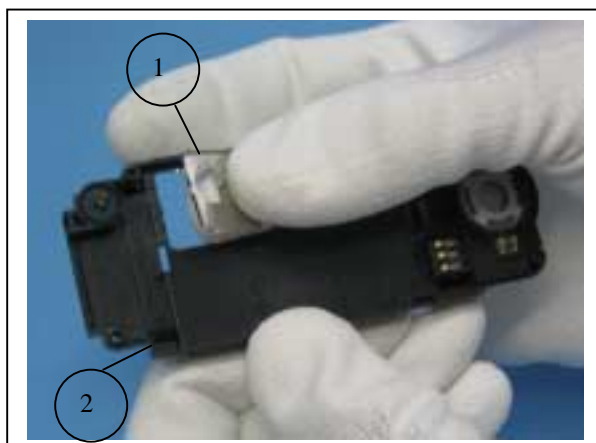
1. On the assembly plate (2), looked at from the battery side ,press firmly the SIM locker (1) until its extraction .
2. Remove the SIM cover (1).

**Placement procedure :**

1. Place the SIM cover (1) in position in its housing.
2. Click fit the SIM cover (1) on the plate.

**Further operations :**

1. Remove the electronic board on the assembly plate.([Proc sheet 1 04](#))
2. Replace the light guide keypad ([Proc sheet 1.03](#))
3. Replace the assembly display ([Proc sheet 1 02](#))
4. Position and tighten the six attachments screws with **0,25 N.m** torque.
5. Replace the front cover /battery / back cover ([Proc sheet 0 01 / 0 02 / 0 03](#)).
6. Carry out the radio test ([Test Sheet 06](#)).





	<b>REMOVING / REPLACING THE BATTERY CONNECTOR</b>	Proc Sheet 1 07
myX 2-2		1/1

**Tools :**

- A 0.6mm torx screwdriver
- Tweezers

**Preliminary operation**

1. Remove the back cover ( [Proc sheet 0 01](#)).
2. Remove the battery ( [Proc sheet 0 02](#)).
3. Remove the front cover ( [Proc sheet 0 03](#)).
4. Unscrew the six attachment screws on the electronic board.
5. Remove the assembly display , then the light guide keypad ( [Proc sheet 1 02 / 1 03](#) )
6. Remove the electronic board.([Proc sheet 1 04](#))

**Removal procedure :**

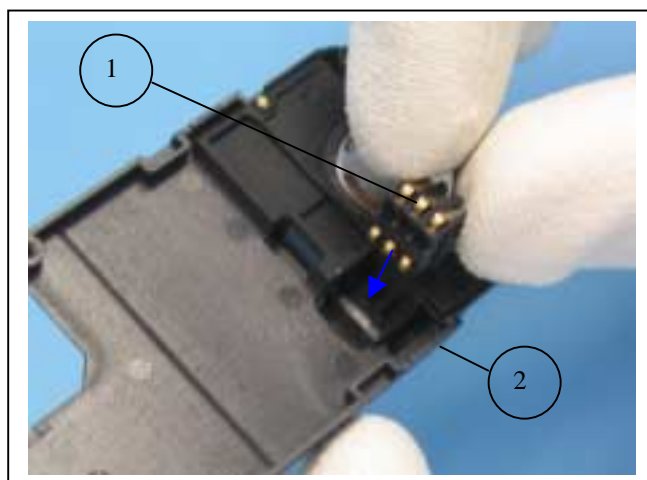
1. Remove the battery connector (1) , using tweezers

**Placement procedure :**

1. Place the battery connector (1) in position in its housing, respecting the foolproof device.

**Further operations :**

1. Remove the electronic board on the assembly plate.([Proc sheet 1 04](#))
2. Replace the light guide keypad ([Proc sheet 1.03](#))
3. Replace the assembly display ([Proc sheet 1 02](#))
4. Position and tighten the six attachments screws with torque settings of **0,25 N.m.**
5. Replace the front cover /battery / back cover ([Proc sheet 0 01 / 0 02 / 0 03](#)).
6. . Carry out the radio test ([Test Sheet 06](#)).



	REMOVING / REPLACING THE MICROPHONE	Proc Sheet 1 08
myX 2-2		1/1

**Tools :**

- A 0.6mm torx screwdriver
- Tweezers

**Preliminary operation**

1. Remove the back cover ( [Proc sheet 0 01](#)).
2. Remove the battery ( [Proc sheet 0 02](#)).
3. Remove the front cover ( [Proc sheet 0 03](#)).
4. Unscrew the six attachment screws on the electronic board.
5. Remove the assembly display , then the light guide keypad ( [Proc sheet 1 02 / 1 03](#) )
6. Remove the electronic board.([Proc sheet 1 04](#))

**Removal procedure:**

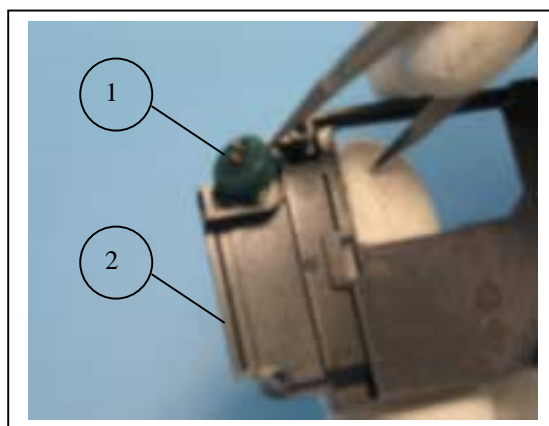
1. Remove the microphone (1) , using tweezers.


**Placement procedure :**

1. Put the microphone (1) in position in its housing (2).

**Further operations :**

1. Remove the electronic board on the assembly plate. .([Proc sheet 1 04](#))
2. Replace the light guide keypad ([Proc sheet 1.03](#))
3. Replace the assembly display ([Proc sheet 1 02](#))
4. Position and tighten the six attachments screws with **0,25 N.m** torque.
5. Replace the front cover /battery / back cover ([Proc sheet 0 01 / 0 02 / 0 03](#)).
6. Carry out the radio test ([Test Sheet 06](#)).



	<b>REMOVING / REPLACING THE LOUDSPEAKER/ VIBRATING DEVICE</b>	Proc Sheet 1 09
myX 2-2		1/1

**Tools :**

- A 0.6mm torx screwdriver
- Tweezers

**Preliminary operation**

1. Remove the back cover ( [Proc sheet 0 01](#)).
2. Remove the battery ( [Proc sheet 0 02](#)).
3. Remove the front cover ( [Proc sheet 0 03](#)).
4. Unscrew the six attachment screws on the electronic board.
5. Remove the assembly display , then the light guide keypad ([Proc sheet 1 02 / 1 03](#))
6. Remove the electronic board.([Proc sheet 1 04](#))

**Removal procedure :**

**Notice: do not touch the loudspeaker diaphragm**

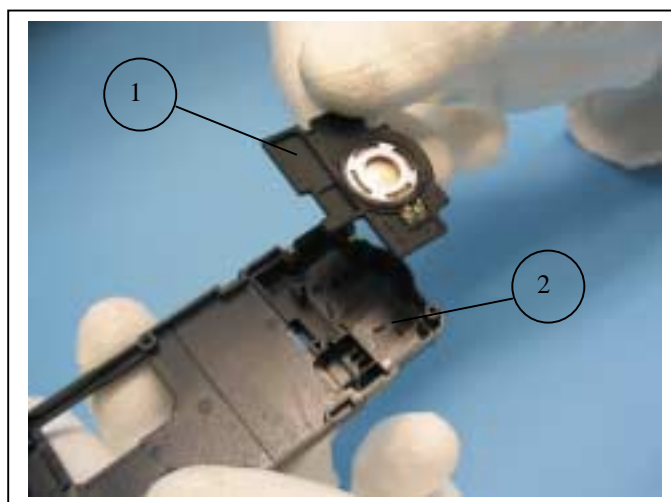
1. Remove, the equipped loudspeaker/ vibrating device (1) in its housing (2).


**Placement procedure :**

1. Put the loudspeaker/ vibrating device in its housing, respecting the foolproof device

**Further operations :**

1. Remove the electronic board on the assembly plate. .([Proc sheet 1 04](#))
2. Replace the light guide keypad ([Proc sheet 1.03](#))
3. Replace the assembly display ([Proc sheet 1 02](#))
4. Position and tighten the six attachments screws with **0,25 N.m** torque.
5. Replace the front cover /battery / back cover ([Proc sheet 0 01 / 0 02 / 0 03](#)).
6. Carry out the radio test ([Test Sheet 06](#)).



	ELECTRONIC BOARD EXCHANGE	Proc Sheet 1 10
myX 2-2		1/3

### ***Preliminary operation***

1. Control of the IMEI label integrity
2. Remove the electronic board (Proc sheet 1 04)
3. Control of any oxidation marks (on the electronic board and under the metal dome)

### ***Return procedure :***

- (a) The electronic boards are packaged in individual electrostatic envelopes. They must be stocked in their original package of reception , to insure a good protection against external attacks (see enclosed photos)
- (b) During the electronic boards manipulation , gloves and electrostatic strap must be worn at all times.
- (c) The defective electronic boards have to be returned to SAGEM factory, packaged individually, in the original package (see enclosed photos) , in the appropriate ESD box : One box per Sagem reference (check reference written on the box).
- (d) The defective board should display the defect code written on a sticker (placed on the shielding) and have the label provided with SMT on each ESD bag .

### ***Note :***


- **On the defective boards , it is necessary to check visually under the metal dome to discover if it shows oxidation marks. The defective boards should be returned with their original metal dome**
- **Boards with oxidation should not to set in conformance with the warranty**
- **The defective boards must never be mixed with the complete mobiles**

### ***Placement procedure :***

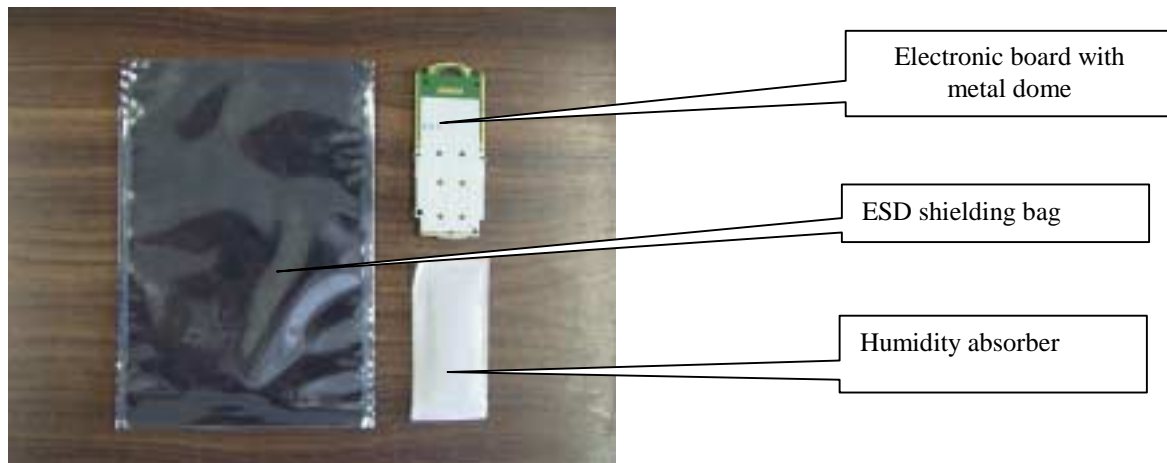
1. Take a board in the stock of swap boards from the same Sagem reference.

### ***Further operations :***

1. Place the new electronic board on the assembly plate. .([Proc sheet 1 04](#))
2. Replace the customer housing (Proc Sheet 0 03 et 1 01)
3. Follow stages ( see enclosed photos)

	<b>ELECTRONIC BOARD EXCHANGE</b>	Proc sheet 1 10
myX 2-2		2/3

*Example of electronic boards packaging :*



Boards packaging SAGEM -> ARC

Boards packaging ARC -> SAGEM




ESD shielding bag closed by the product label



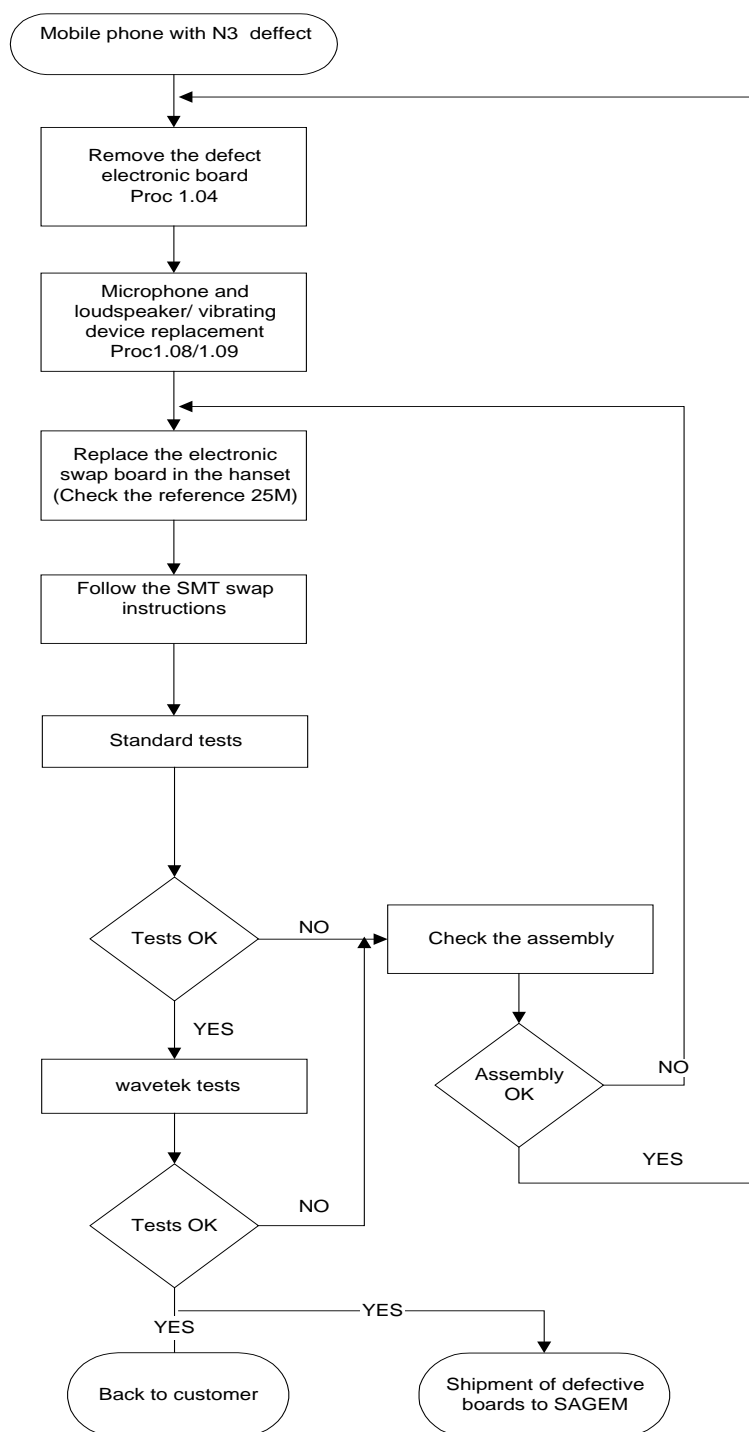
ESD shielding bag closed by the IMEI label



SAGEM electrostatic shielding box  
Reference 20 boards: 27441180-4  
Reference 100 boards: 27 511110-6

	ELECTRONIC BOARD EXCHANGE	Proc sheet 1 10
myX 2-2		3/3

## Electronic board exchange process



Detection of N3 defect : See the Technical documentation

-Check oxidation under the metal dome .

- Audio parameters written on the new swap board

- Display test : Hot Line Menu  
- Keypad test  
- Vibrating device test

- See Technical documentation (test sheet 06)

- Follow return instructions page 5-32

# **LEVEL 3 MAINTENANCE**

## **IMPORTANT**

### **Mobile packaging sent to SAGEM S.A. :**

Follow the Proc sheet 1.10


### **Packaging for swap or mobile components storage :**

The swap and the mobile components must be stored with a particular care especially for the most sensible component (Display , loudspeaker etc...).



**(Mandatory)**

This form must be attached around the defective mobile or the ESD bag containing the defective board:  
it must not be put inside the ESD bag.

<b>ARC INFORMATION</b>	
ARC Name .....	
ARC Address.....	
ARC Country.....	
ARC Phone nr.....	
<b>PRODUCT INFORMATION</b>	
Warranty.....	<input type="checkbox"/> YES <input type="checkbox"/> NO
Product name.....	_____
Product reference.....	_____
IMEI.....	 * 3 5 1 2 3 1 2 3 1 2 3 0 0 0 0 *
Date of purchase.....	...../...../.....
Incoming date in ARC.....	...../...../.....
Last swap date (if applicable, <3 month)	...../...../.....
Defect code found by ARC.....	<div style="display: flex; justify-content: space-around;"> <div><input type="text"/></div> <div><input type="text"/></div> </div>
Second NFF Return .....	<input type="checkbox"/> YES <input type="checkbox"/> NO

Code SAGEM	Type de défauts	Type of fault
<b>PROBLEME D'AFFICHAGE</b>		<b>DISPLAY PROBLEM</b>
A1	PAS D'AFFICHAGE - LCD INTERNE DEFECTUEUX	NO POWER UP - DEFECTIVE INTERNAL LCD
A3	BLOCAGE DE L'AFFICHAGE LCD INTERNE	FREEZES UP INTERNAL LCD
A5	AFFICHEUR CASSE LCD INTERNE	BROKEN INTERNAL LCD
A6	LIGNE, DIGIT OU PIXEL MANQUANT, CONTRASTE, COULEUR LCD INTERNE	MISSING LINE, DIGIT or PIXEL, CONTRAST, COLOR INTERNAL LCD
A7	PB RETROECLAIRAGE LCD INTERNE	BACKLIGHT'S PROBLEM INTERNAL LCD
A11	PAS D'AFFICHAGE LCD EXTERNE DEFECTUEUX	NO POWER UP - DEFECTIVE EXTERNAL LCD
A13	BLOCAGE DE L'AFFICHAGE LCD EXTERNE	FREEZES UP EXTERNAL LCD
A14	AFFICHEUR CASSE LCD EXTERNE	BROKEN EXTERNAL
A15	LIGNE, DIGIT OU PIXEL MANQUANT, CONTRASTE, COULEUR LCD EXTERNE	MISSING LINE, DIGIT or PIXEL, CONTRAST, COLOR EXTERNAL LCD
A16	PB RETROECLAIRAGE LCD EXTERNE	BACKLIGHT'S PROBLEM EXTERNAL LCD
<b>PROBLEME D'ANTENNE</b>		<b>ANTENNA PROBLEM</b>
A10	ANTENNE CASSEE / ABSENTE	BROKEN / MISSING ANTENNA
<b>PROBLEME D'ALIMENTATION / CHARGEUR</b>		<b>POWER SUPPLY / CHARGING PROBLEM</b>
B1	CONTACT BATTERIE DU MOBILE DEFECTUEUX	DEFECTIVE MOBILE BATTERY CONTACT
B2	CONNECTEUR DE CHARGE DU MOBILE DEFECTUEUX	DEFECTIVE MOBILE CHARGER CONNECTOR
B3	ALIMENTATION CARTE DEFECTUEUSE	DEFECTIVE POWER SUPPLY OF THE BOARD
B4	AFFICHAGE CHARGE DEFECTUEUX	DEFECTIVE CHARGE ICON DISPLAY
B5	CONSOMMATION MODE ETENDU	CURRENT CONSUMPTION WITH PHONE OFF
B7	PROBLEME D'AUTONOMIE	INSUFFICIENT BATTERY DURATION
B8	BATTERIE DEFECTUEUSE	ELECTRICALLY DEFECTIVE BATTERY
B9	TENUE MECANIQUE BATTERIE	MECHANICAL LOCK PROBLEM ON BATTERY
B10	BATTERIE CASSEE	BROKEN BATTERY
B11	CHARGEUR DEFECTUEUX	DEFECTIVE CHARGER
B12	CHARGEUR CASSE	BROKEN CHARGER
B13	COUPURE INTERMITTENTE AVEC REDEMARRAGE	INTERMITTENT SWITCH OFF WITH REBOOT
B14	COUPURE INTERMITTENTE SANS REDEMARRAGE	INTERMITTENT SWITCH OFF WITHOUT REBOOT
<b>PROBLEME DE CLAVIER</b>		<b>KEYBOARD PROBLEM</b>
C1	CLAVIER INOPERANT CORPS PRINCIPAL	NOT FUNCTIONING BODY KEYBOARD
C2	PROBLEME TOUCHÉ LATÉRALE	SIDE KEY PROBLEM
C3	CLAVIER INOPERANT FLAP/SLIDE	NOT FUNCTIONING FLIP OR SLIDE KEYBOARD
<b>MESSAGE D'ERREUR</b>		<b>ERROR MESSAGE</b>
D1	SIM ABSENTE	SIM MISSING
D2	AUTRES MESSAGES	OTHER MESSAGES
D4	MOBILE NON REÇU	UNUSED MOBILE
D6	SIM VERROU	SIM LOCK
D7	CODE POSTÉ	POST CODE BLOCKED
D8	RETOUR SAV	SAV RETURN
<b>PROBLEME AUDIO</b>		<b>AUDIO PROBLEM</b>
E1	HP DEFECTUEUX	DEFECTIVE LOUDSPEAKER (Halls)
E3	MICRO DEFECTUEUX	DEFECTIVE MICROPHONE
E5	PROBLEME DE VIBREUR	VIBRATING DEVICE PROBLEM
E6	CONNECTEUR AUDIO DEFECTUEUX	DEFECTIVE AUDIO CONNECTOR
<b>PROBLEME DE COMMUNICATION</b>		<b>COMMUNICATION PROBLEM</b>
F1	PAS DE LOCALISATION RESEAU	NO NETWORK RETRIEVAL
F2	COUPURE DE COMMUNICATION	INTERMITTENT CALLS DROP
F4	TEST RADIO NON OK	TEST RADIO NO OK
F5	ECHEC APPEL SORTANT	OUT GOING CALL FAILURE
F6	ECHEC APPEL ENTRANT	INCOMING CALL FAILURE
F7	PERTE TEMPORAIRE DE RESEAU	NETWORK TEMPORARY DROP
<b>PROBLEME COSMETIQUE / DEFAUT VISUEL</b>		<b>COSMETIC PROBLEM</b>
G1	VITRE CASSEE OU ABIMEE CORPS PRINCIPAL	BROKEN OR DAMAGED BODY GLASS
G2	COQUE CASSEE OU ABIMEE	BROKEN OR DAMAGED COVER
G3	FLAP CASSE OU ABIME	BROKEN OR DAMAGED FLIP
G5	CLAVIER CASSE OU ABIME CORPS PRINCIPAL	BROKEN OR DAMAGED BODY KEYBOARD
G6	BOUTON VERROU DEFECTUEUX	DEFECTIVE LOCK BUTTON
G7	VITRE CASSEE OU ABIMEE FLAP/SLIDE	BROKEN OR DAMAGED GLASS FLIP/SLIDE
G8	CLAVIER CASSE OU ABIME FLAP/SLIDE	BROKEN OR DAMAGED FLIP/SLIDE KEYBOARD
<b>AUTRES PROBLEMES</b>		<b>OTHER PROBLEM</b>
H1	KIT ACCESSOIRES HS (KIT PIETON CLASSIQUE, KITS BLUETOOTH...)	BROKEN OR DAMAGED ACCESSORY (PEDESTRIAN HEADSET, BLUETOOTH KITS...)
H2	FONCTION FM (MOBILE) OU MP3	FM OR MP3 FUNCTION (Mobile)
I1	TRACE D'OXYDATION	OXYDATION MARKS
I3	PAS DE DEFAUT CONSTATE	NO FAULT FOUND
I10	PAS DE DEFAUT CONSTATE SECOND RETOUR (sauf pendant la boucle courte)	NO FAULT FOUND SECOND RETURN (excepted during short loop process)
I5	MANQUE FONCTION DANS MENU	LACK FUNCTION IN THE MENU
I6	CONNECTEUR SIM DEFECTUEUX	DEFECTIVE SIM CONNECTOR
I7	DYSFONCTIONNEMENT D'UNE FONCTION DU MENU	MAFUNCTION OF THE MENU
I8	RECONFIGURATION DU MOBILE	MOBILE RETROFIT
I9	BLACK LIST	BLACK LIST
<b>PROBLEME MULTIMEDIA</b>		<b>MULTIMEDIA PROBLEM</b>
K2	FONCTION VIDEO	VIDEO FUNCTION
K4	FONCTION WAP	WAP FUNCTION
K5	FONCTION GPRS	GPRS FUNCTION
K6	FONCTION SMS, EMS, MMS	SMS, EMS, MMS FUNCTION
K7	NE COMMUNIQUE PAS AVEC UN PC	NO COMMUNICATION WITH A PC
K8	NE COMMUNIQUE PAS AVEC UN POCKET PC OU PALM	NO COMMUNICATION WITH A POCKET PC or PALM
K9	LIAISON DATA (MESSAGE "AUCUNE PORTEUSE DETECTEE")	DAT A (MESSAGE "NO CARRIER DETECTED")
K10	TELECHARGEMENT JEUX	DOWNLOADING GAME
K11	TELECHARGEMENT IMAGE / SON / ECONOMISEUR D'ECRAN	DOWNLOADING PICTURE / RINGTONE / SCREEN SAVER
K12	PB DATA SANS FIL (IRDA, BLUETOOTH...)	WIRELESS DATA FUNCTION PB (IRDA, BLUETOOTH...)
K13	PB CONNECTIQUE SLOT I/O (SD/MMC)	SLOT I/O PB (SD/MMC)

# **OUT OF WARRANTY INTERVENTION**

	<b>REMOVING/ REPLACING THE SMK CONNECTOR</b>	Proc Sheet 4 01
myX 2-2		1/3

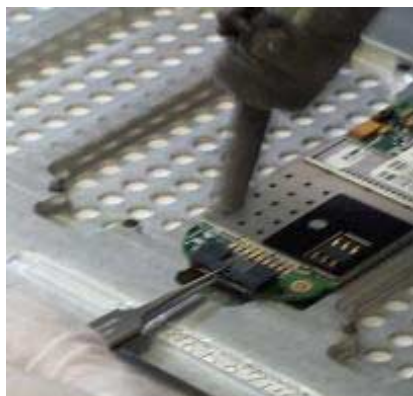
**Notice:** The handsets requiring the replacement of system connectors cannot be repaired under Sagem warranty.

The eventual deterioration of the board due to a bad replacement of the connector fall under the Repair Centre responsibility.

**- Replacement procedure of SMK connector**

- 1-Disassemble the handset Proc 1 04
- 2-Replace the defective connector (see below) **Ref 18 598 906-8**
- 3 - Replace the electronic board in the mobile phone Proc 1 04
- 4 -To test the replacement of the connector, it is necessary to:
  - a) Connect the mobile phone on SMT maintenance software (test Sheet 01)
  - b) Make real calls with a pedestrian handsfree Kit **Reference :23 812 517-0**
  - c) Test the charge of mobile phone
- 5 - Standard test after repair

	<b>REMOVING/ REPLACING THE SMK CONNECTOR</b>	Proc Sheet 4 01
myX 2-2		2/3



- Maintain the electronic board
  - flux Correctly the pins of the connector.
  - Reference of the flux to be used:
  - LITTON flux -Supplier reference 952-D6
  - SAGEM reference 18 775 103-7
  - With tweezers, hold the connector and heat the pins up.
- ATTENTION:**
- Do not pull the connector but let it come , in order to avoid destroying the pads



After having removed the connector, uncork rather quickly the four holes of the connector while the tin is still warm.



Flux and heat the pads in place of the connector to equalise the foot prints



In order to tin the pins of the SMK , load the solder wick with tin on approximately 1 inch.

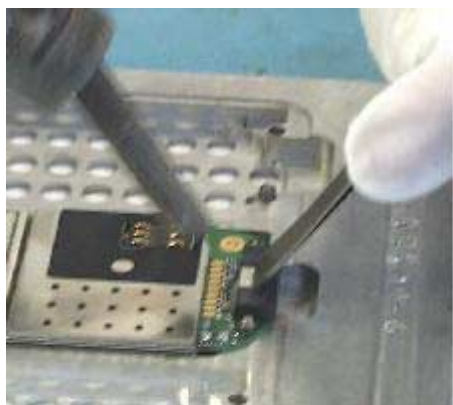
	<b>REMOVING/ REPLACING THE SMK CONNECTOR</b>	Proc Sheet 4 01
myX 2-2		3/3



Before any operation,  
- flux correctly the pins of the connector.  
- with the solder wick loaded with tin , tin the pins of the SMK by positioning it straight ahead (pads upward), and by heating the solder wick which is in touch with pins.

**Attention:**

- At the end of the operation , verify that there is no short circuit between pads.



-Start soldering the connector pins.  
-Flux the place of the connector and position the SMK.  
-Verify that the pins of the SMK are well centred on pads.  
-Heat pins with an air blow device while maintaining the connector with tweezers  
-Verify that there is no short-circuit, that solders are shiny and that they cover well the pins



At last, solder the 4 pins crossing the board..